

Fig.1

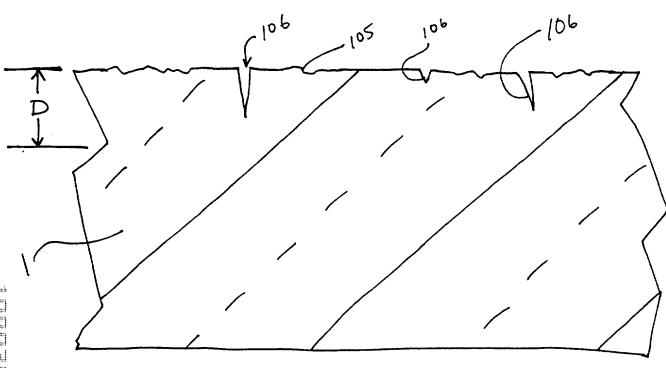
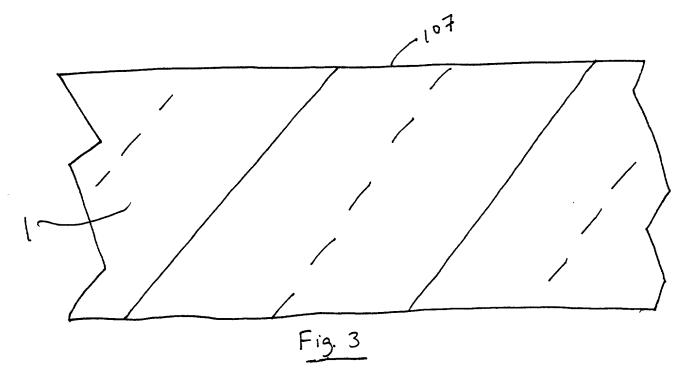
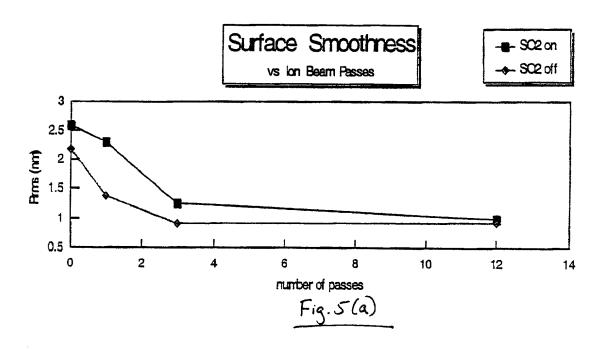


Fig. 2





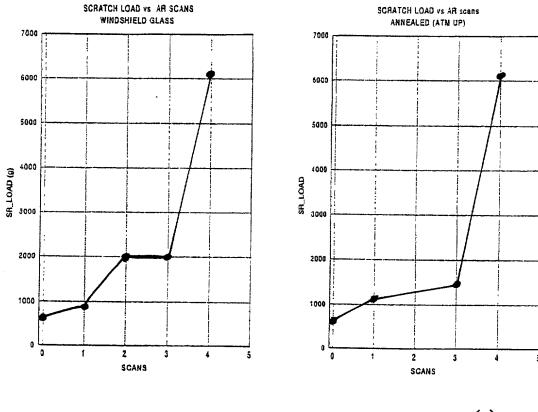
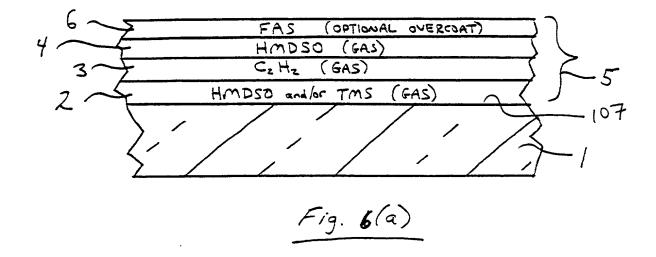
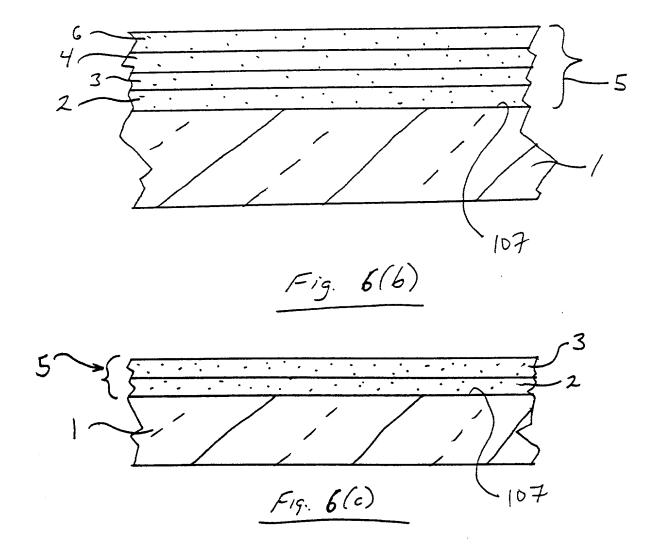


Fig. 5(6)

Fig. 5(c)





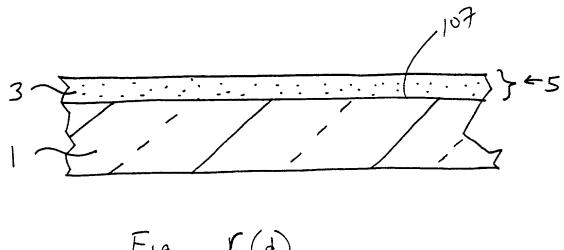
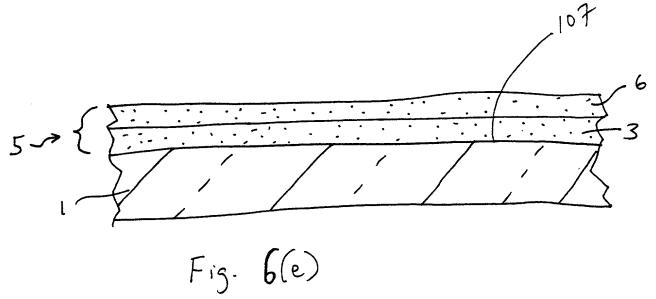


Fig. 6(d)



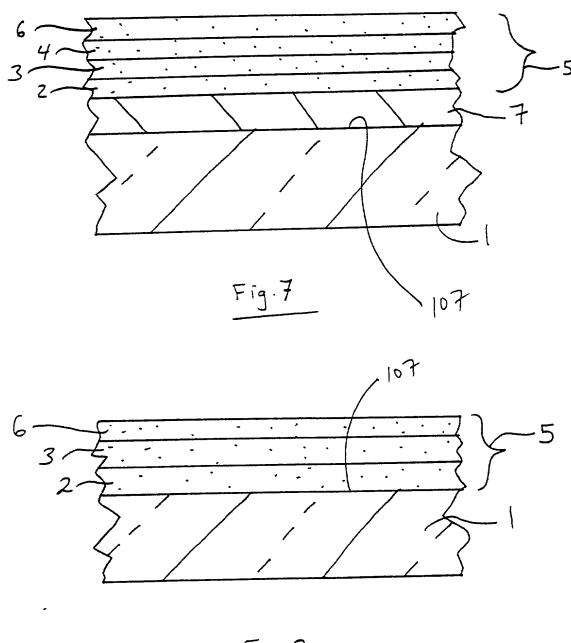
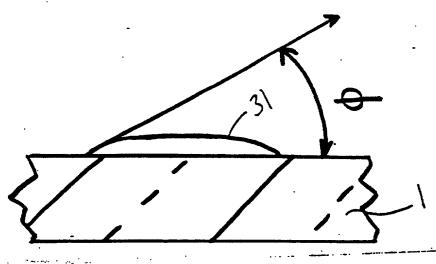
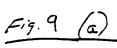
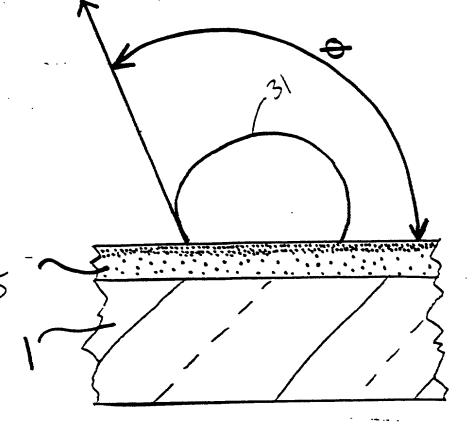


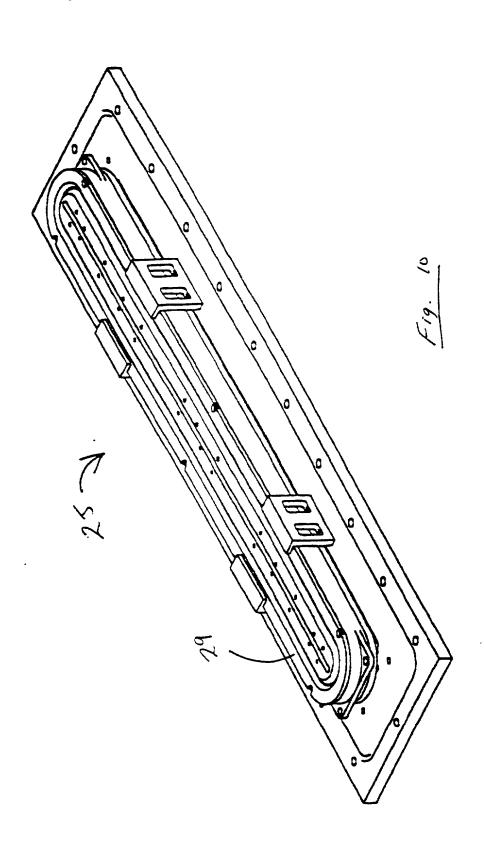
Fig. 8

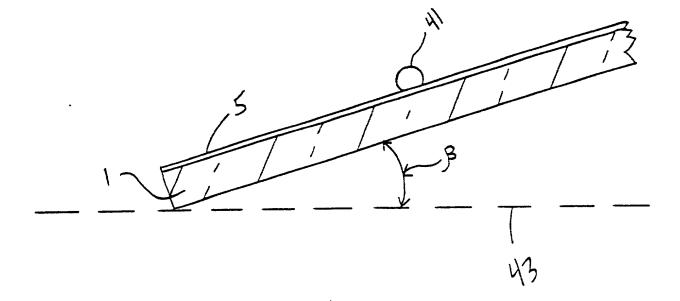






F19.9 (b)





F19. 12

Fig. 13

PROVIDE SUBSTRATE. DEPOSIT AT LEAST ONE DLC INCLUSIVE LAYER ON THE SUBSTRATE DEPOSIT AT LEAST ONE FAS INCLUSIVE LAYER ON THE SUBSTRATE CUER THE DIC INCLUSIVE LAYER THERMALLY CURE AT LEAST THE FAS INCLUSIVE LAYER TO IMPROVE CONTACT ANGLE ANDLOR BONDING CHARACTERISTICS OF

THE RESULTING COATED ARTICLE

$$\frac{Fig. \quad 14}{HMDSO}$$

$$CH_3 \qquad CH_3$$

$$CH_3 \qquad CH_3$$

$$CH_3 \qquad CH_3$$

TMDSO Fig. 19

$$H$$
 CH_3 Si O Si CH_3
 CH_3

$$\begin{array}{c|c}
OCH_2CH_3 \\
\hline
OCH_2CH_3 \\
\hline
OCH_2CH_3
\end{array}$$

Provide Glass Substrate

Heat Substrate to 100-400°C

Deposit DLC inclusive
layer (s) on substrate when
substrate is heated, using
ion bean deposition

· Fig. 21